

AN-2200 LM5017 Evaluation Board

1 Introduction

The LM5017 evaluation board provides the design engineer with a fully functional buck regulator, employing the constant on-time (COT) operating principle. This evaluation board provides a 10 V output over an input range of 12.5 V to 100 V.

The board's specifications are:

- Input Range: 12.5 V to 95 V, transients up to 100 V (absolute maximum)
- Output Voltage: 10 V
- Output Current: 600 mA
- Nominal Switching Frequency ~ 200 kHz
- Measured Efficiency: 92.4% at 400 mA and $V_{IN} = 24$ V
- Board size: 2.95 in. x 1.8 in.

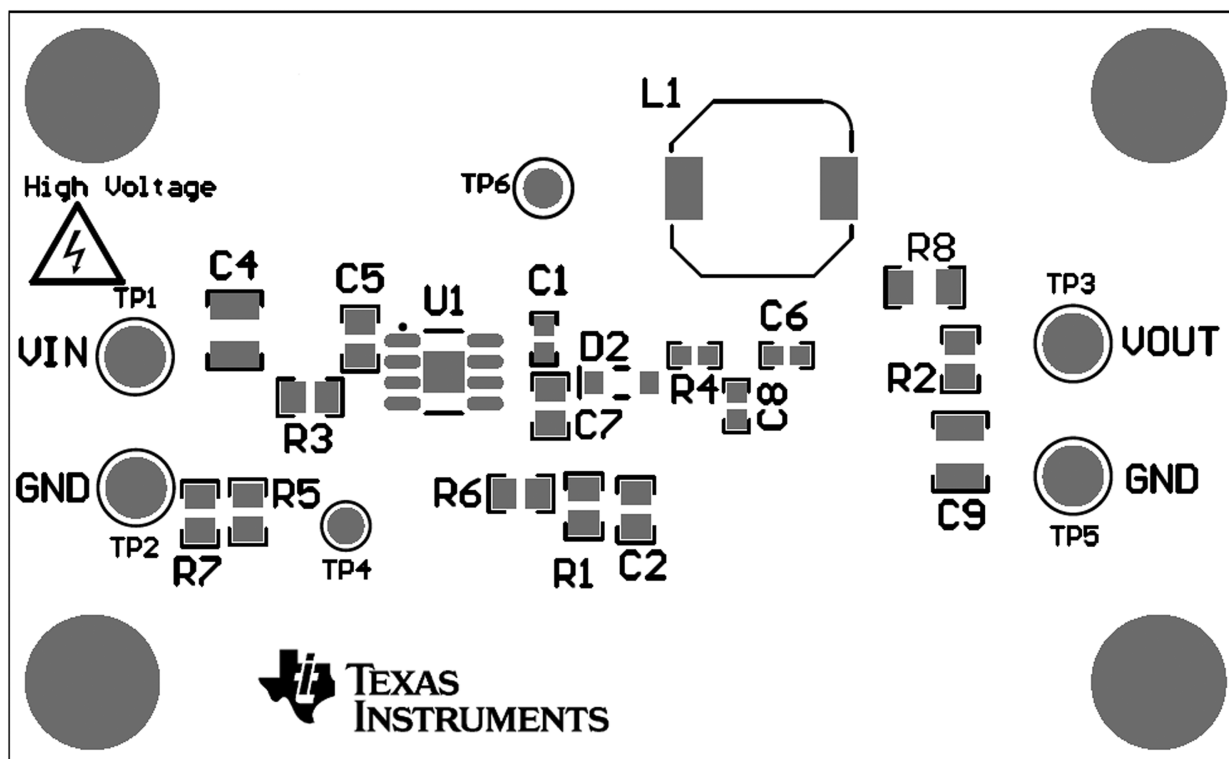


Figure 1. Evaluation Board (Top View)

2 Theory of Operation

When the circuit is in regulation, the buck switch is turned on each cycle for a time determined by R3 and V_{IN} according to Equation 1:

$$T_{ON} = \frac{10^{-10} \times R3}{V_{IN}} \quad (1)$$

The on-time of this evaluation board ranges from 5.56 μ s at $V_{IN} = 12$ V to 702 ns at $V_{IN} = 95$ V. The on-time varies inversely with input voltage. At the end of each on-time, the buck switch is off for at least 144 ns. In normal operation, the off-time is much longer. During the off-time, the load current is supplied by the output capacitor (C9). When the output voltage falls sufficiently that the voltage at FB is below 1.225 V, the regulation comparator initiates a new on-time period. For stable, fixed frequency operation, a minimum of 25 mV of ripple is required at FB to switch the regulation comparator. For a more detailed block diagram and a complete description of the various functional blocks, see the *LM5017 100V, 600mA Constant On-Time Synchronous Buck Regulator Data Sheet* ([SNVS783](#)).

3 UVLO

The UVLO resistors (R5, R7) are selected using Equation 2:

$$V_{IN(HYS)} = I_{HYS}R_5 \quad (2)$$

and Equation 3:

$$V_{IN(UVLO, rising)} = 1.225V \times \left(\frac{R_5}{R_7} + 1 \right) \quad (3)$$

On this evaluation board, R5 = 127 k Ω and R7 = 14.0 k Ω , resulting in UVLO rising threshold at $V_{IN} = 12$ V and a hysteresis of 2.5 V.

Figure 2 shows the evaluation board schematic.

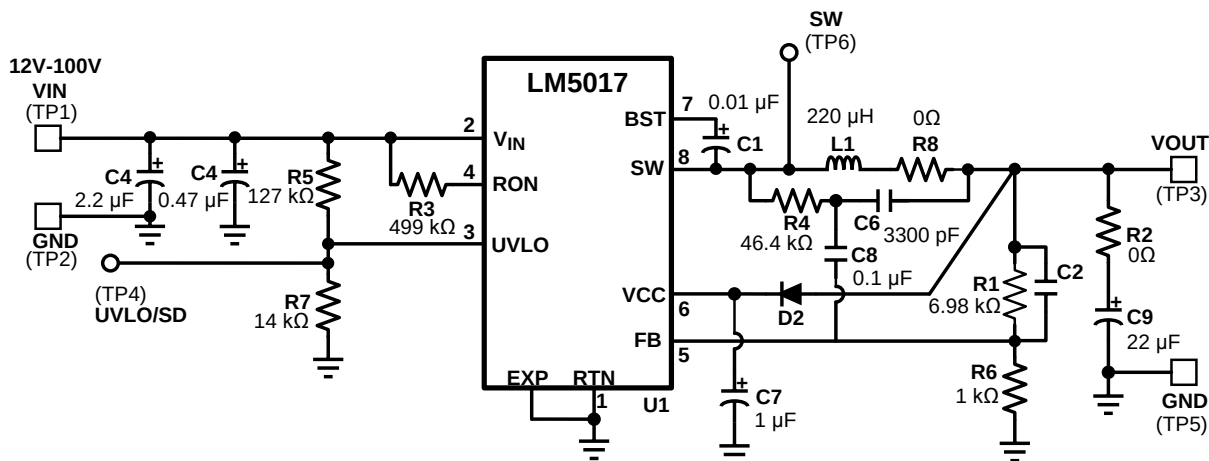


Figure 2. Complete Evaluation Board Schematic for LM5017-Based Buck Converter

4 Board Connection and Start-up

The input connections are made to the TP1 (V_{IN}) and TP2 (GND) terminals. The load is connected to the TP3 (V_{OUT}) AND TP5 (GND) terminals. Ensure the wires are adequately sized for the intended load current. Before start-up, a voltmeter should be connected to the input and output terminals. The load current should be monitored with an ammeter or a current probe. It is recommended that the input voltage be increased gradually to 12 V, at which time the output voltage should be 10 V. If the output voltage is correct, increase the input voltage as desired and proceed with evaluating the circuit. DO NOT EXCEED 100 V AT V_{IN} .

Table 1. Bill of Materials (BOM)

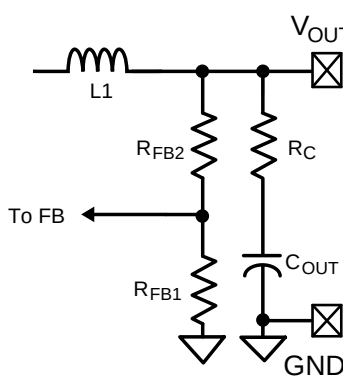
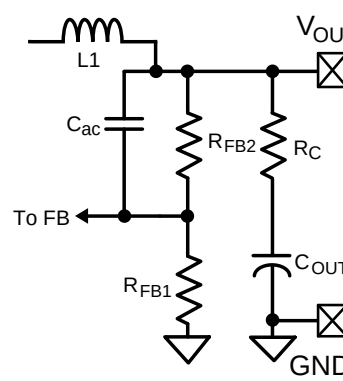
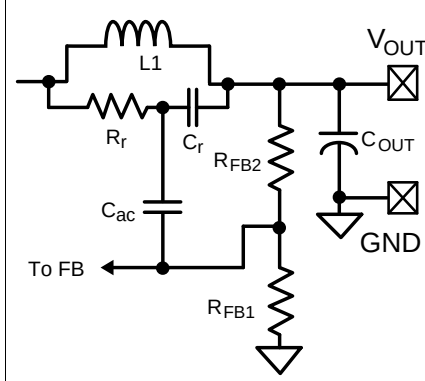
Item	Description	Mfg. Part Number	Package	Value
U1	Sync Switching Regulator	Texas Instruments, LM5017	SO PowerPAD-8	100 V, 0.6A
L1	Inductor	Wurth, 7447714221	10 mm x 10 mm	220 μ H, 1.2A
	Alternate Inductor	Bourns, SRR1260–221k	12.5 mm x 12.5 mm	220 μ H, 1.38A
	Alternate Inductor	Coilcraft, MSS1246–224K	12.3 mm x 12.3 mm	220 μ H, 1.4A
D2	Diode	Central Semi, CMMSH1–40	SOD-123F	40 V, 1A
	Alternate Diode	NXP, BAS40H, 115	SOD123F	40 V, 120 mA
C1	Ceramic Capacitor	Murata, GRM188R71C103KA01D	0603	0.01 μ F, 16V, X7R
C2				NA
C4	Ceramic Capacitor	Murata, GRM32ER72A225KA35L	1210	2.2 μ F, 100 V, X7R
C5	Ceramic Capacitor	Murata, GRM21BR72A474KA73L	0805	0.47 μ F, 100 V, X7R
C6	Ceramic Capacitor	TDK, C1608X7R1H332K	0603	3300 pF, 50 V, X7R
C7	Ceramic Capacitor	TDK, C2012X7R1C105K	0805	1 μ F, 16 V, X7R
C8	Ceramic Capacitor	Murata, GRM188R71E104KA01D	0603	0.1 μ F, 25 V, X7R
C9	Ceramic Capacitor	Murata, GRM32ER71E226KE15L	1210	22 μ F, 25 V, X7R
R1	Resistor	Vishay–Dale, CRCW08056K98FKEA	0805	6.98k Ω , 1%
R2	Resistor	Panasonic, ERJ-6GEY0R00V	0805	0 Ω
R3	Resistor	Panasonic, ERJ-6ENF4993V	0805	499k Ω , 1%
R4	Resistor	Panasonic, ERJ-3EKF4642V	0603	46.4k Ω , 1%
R5	Resistor	Vishay-Dale, CRCW0805127KFKEA	0805	127k Ω , 1%
R6	Resistor	Vishay-Dale, CRCW08051K00FKEA	0805	1.0k Ω , 1%
R7	Resistor	Vishay-Dale, CRCW080514K0FKEA	0805	14.0k Ω , 1%
R8	Resistor	Yageo, RC1206JR-070RL	1206	0 Ω

5 Ripple Configuration

The LM5017 is a COT buck and requires adequate ripple at feedback (FB) node. Three commonly used ripple generation methods are shown in [Table 2](#).

LM5017 evaluation board has been supplied with minimum ripple configuration (Type 3), but can be configured to Type 1 or Type 2 with modifications as suggested in [Table 2](#).

Table 2. Ripple Configuration

Type 1 Lowest Cost Configuration	Type 2 Reduced Ripple Configuration	Type 3 Minimum Ripple Configuration
		
R4, C6, C8 open. Select R2: $R2 \geq \frac{40 \text{ mV}}{\Delta I_L(\text{MIN})} \times \frac{V_{\text{OUT}}}{V_{\text{REF}}} \quad (4)$	R4 open, C6 = 0 Ω. Select R2 and C8: $C8 \geq \frac{5}{f_{\text{SW}}(R1 \parallel R6)}$ $R2 \geq \frac{40 \text{ mV}}{\Delta I_L} \quad (5)$	R2 = 0 Ω. Select R4, C6, and C8: $C6 = 3300 \text{ pF}$ $C8 = 100 \text{ nF}$ $R4 \times C6 \leq \frac{(V_{\text{IN}(\text{MIN})} - V_{\text{OUT}})T_{\text{ON}}}{40 \text{ mV}} \quad (6)$

6 Performance Curves

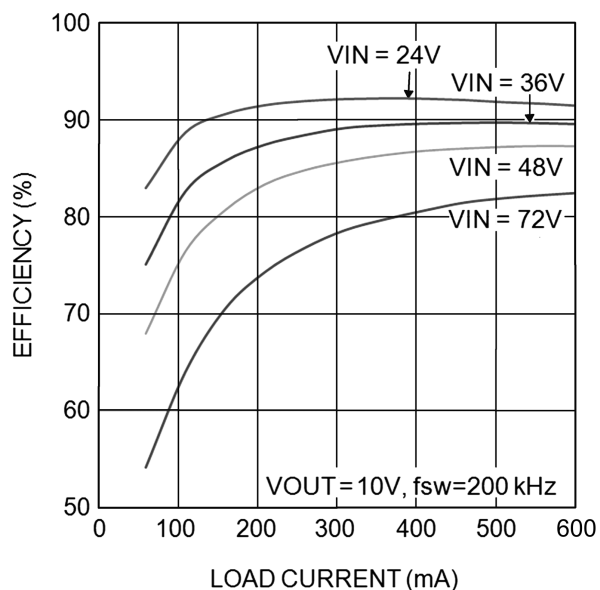


Figure 3. Efficiency vs Load Current

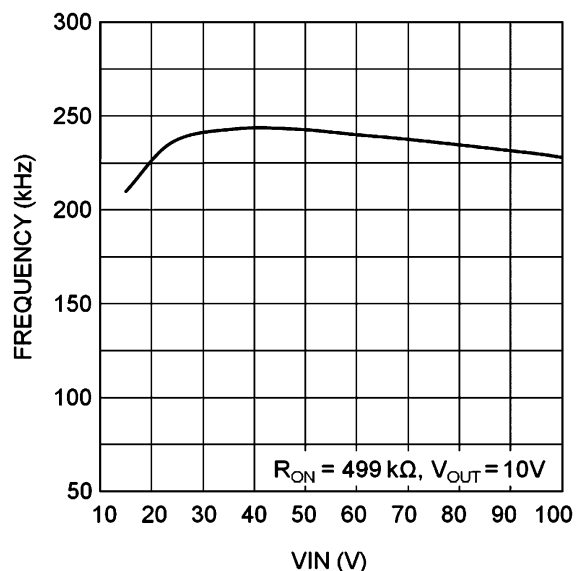


Figure 4. Frequency vs Input Voltage

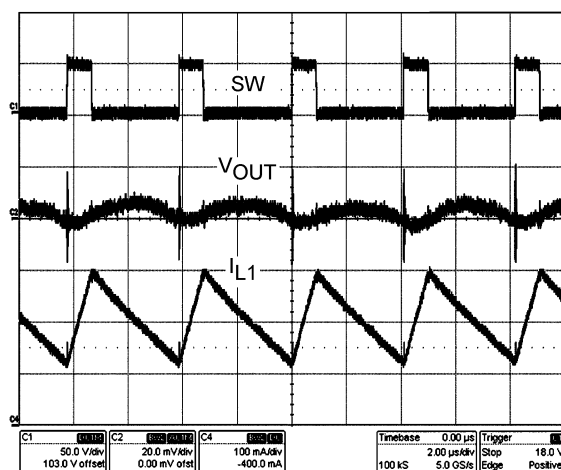


Figure 5. Typical Switching Waveform ($V_{IN} = 48\text{ V}$, $I_{out} = 200\text{ mA}$)

7 PC Board Layout

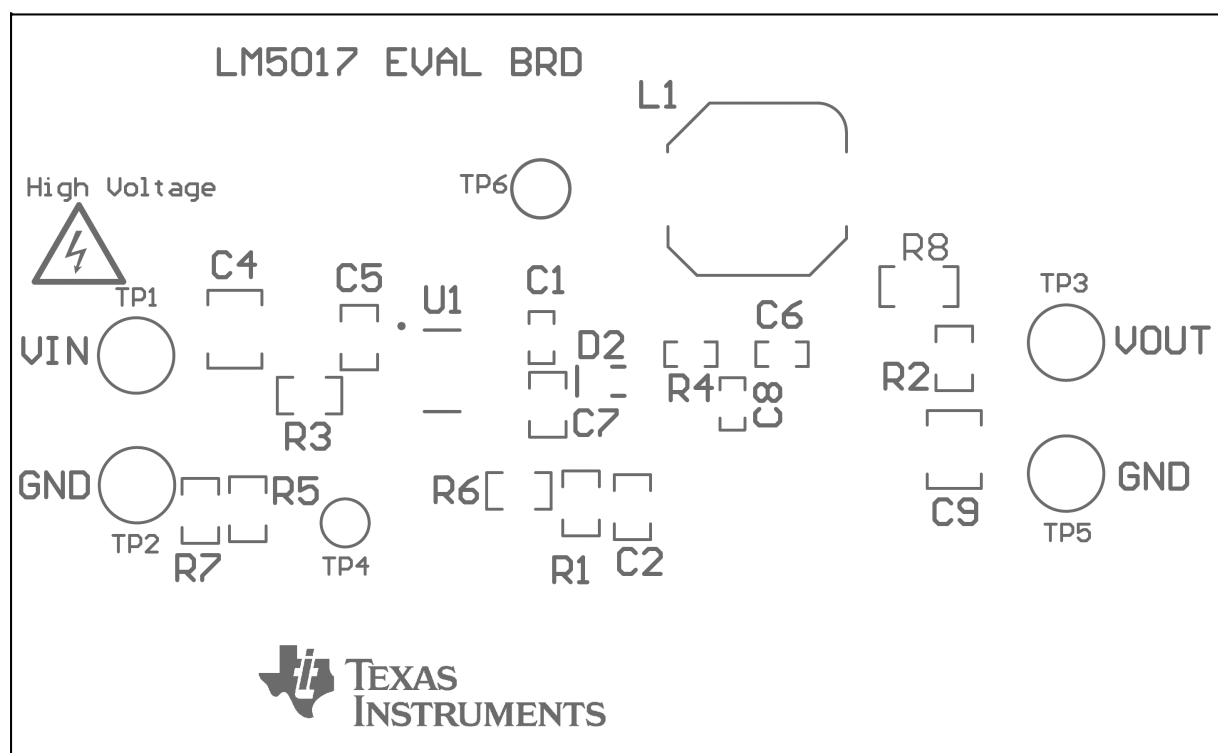


Figure 6. Board Silkscreen

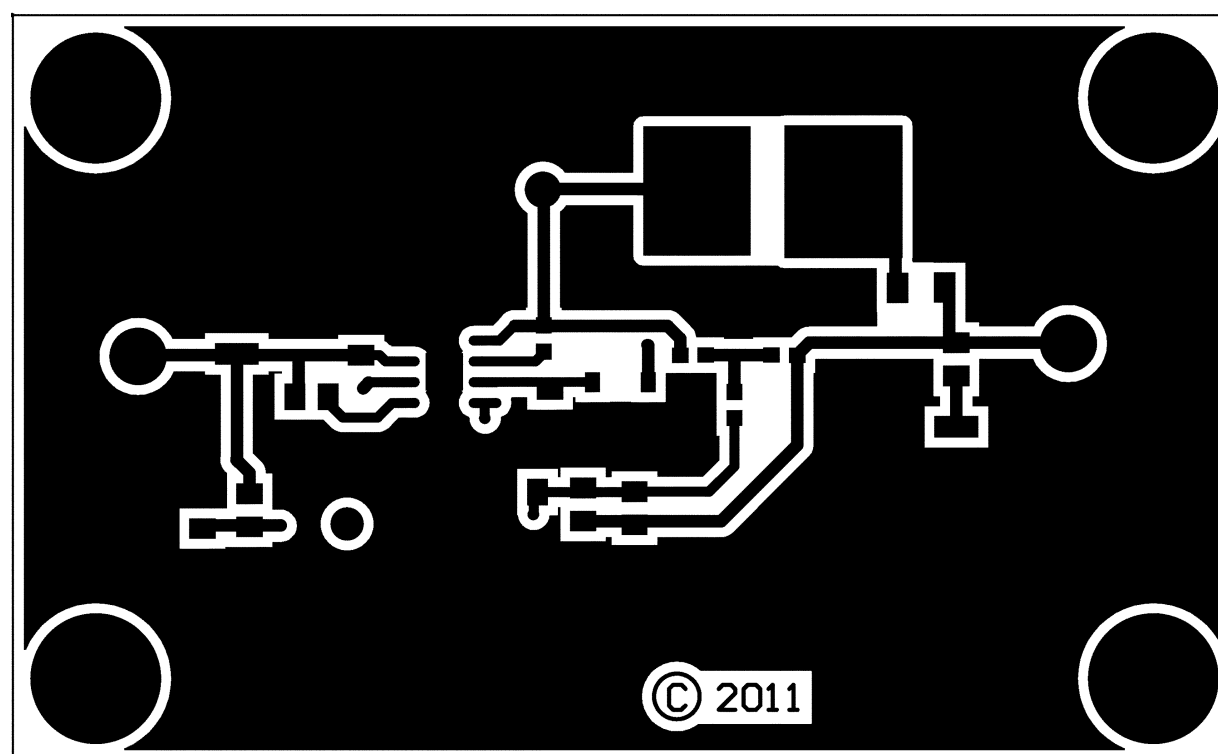


Figure 7. Board Top Layer

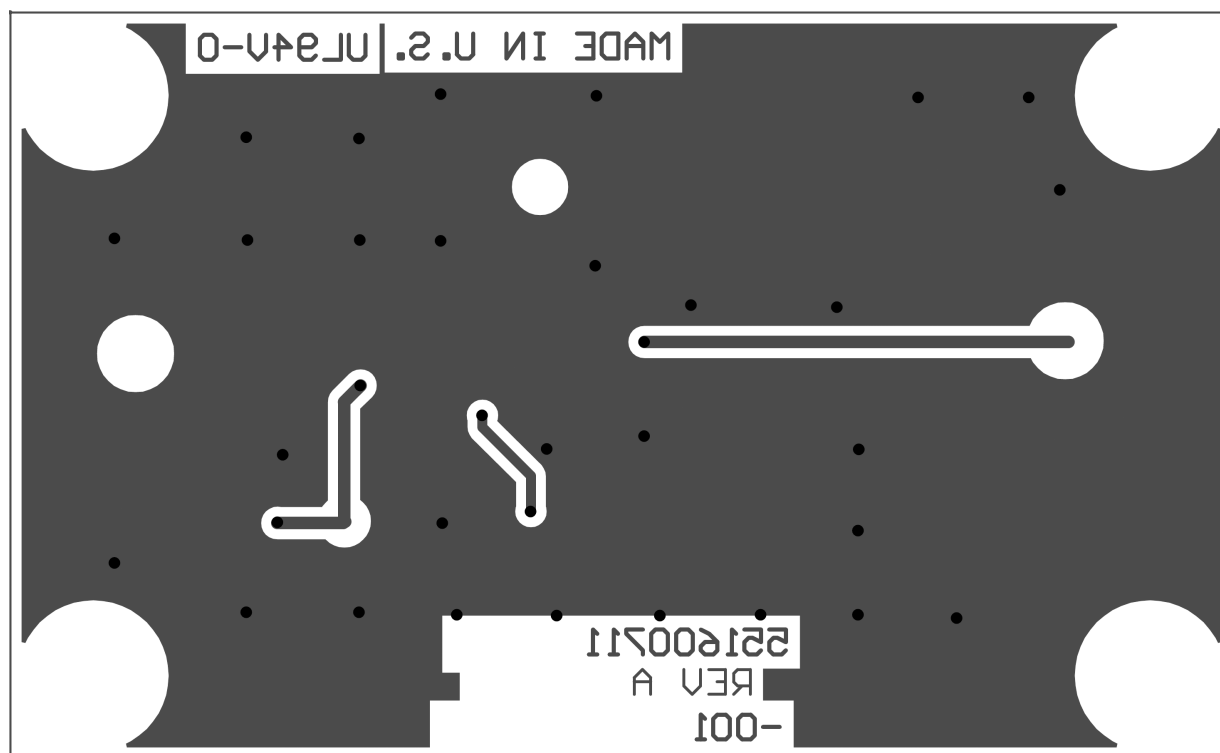


Figure 8. Board Bottom Layer

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